1.6X0.8mm SMD CHIP LED LAMP (0.25mm Height)

PRELIMINARY SPEC

Part Number: APG1608SEKC/T

Super Bright Orange

Features

- 1.6mmX0.8mm SMT LED, 0.25mm thickness.
- Low power consumption.
- Wide viewing angle.
- Compatible with automatic placement equipment.
- Ideal for backlight and indicator.
- Package: 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

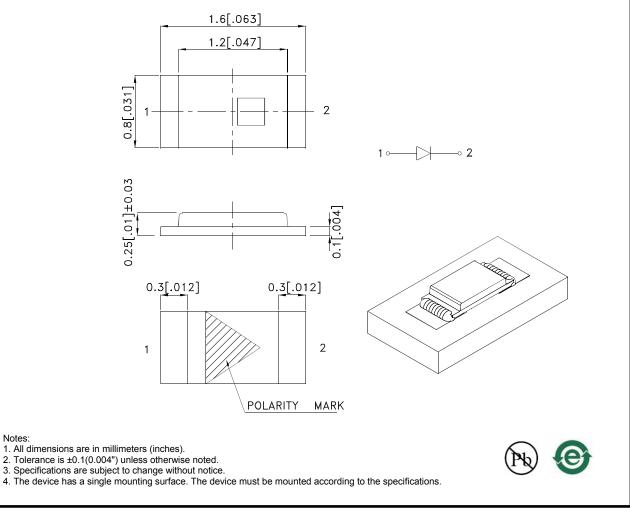
Description

The Super Bright Orange device is made with AlGaInP (on GaAs substrate) light emitting diode chip.

Applications

- 1. Mobile phone Keypad indicator and backlight.
- 2.Flat backlight for LCD, switch and symbol.
- 3.Toys.

Package Dimensions



DATE: MAR/30/2009 DRAWN: X.M.He PAGE: 1 OF 5 ERP: 1203007887

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Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
APG1608SEKC/T	Super Bright Orange (AlGaInP)	WATER CLEAR	110	200	120°

Notes:

1. θ /2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value. 2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Orange	610		nm	IF=20mA
λD [1]	Dominant Wavelength	Super Bright Orange	601		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Orange	17		nm	I⊧=20mA
С	Capacitance	Super Bright Orange	15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Super Bright Orange	2.05	2.5	V	I⊧=20mA
lr	Reverse Current	Super Bright Orange		10	uA	Vr=5V

Notes:

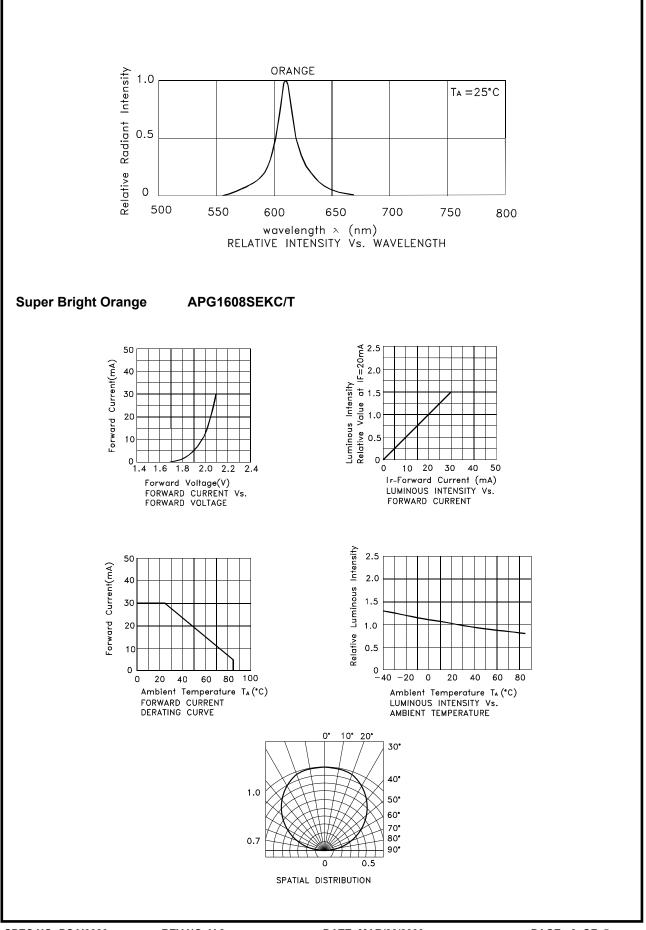
1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

Parameter	Super Bright Orange	Units	
Power dissipation	75	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	150	mA	
Reverse Voltage	5	V	
Operating Temperature	-40°C To +85°C		
Storage Temperature	-40°C To +85°C		

Note:

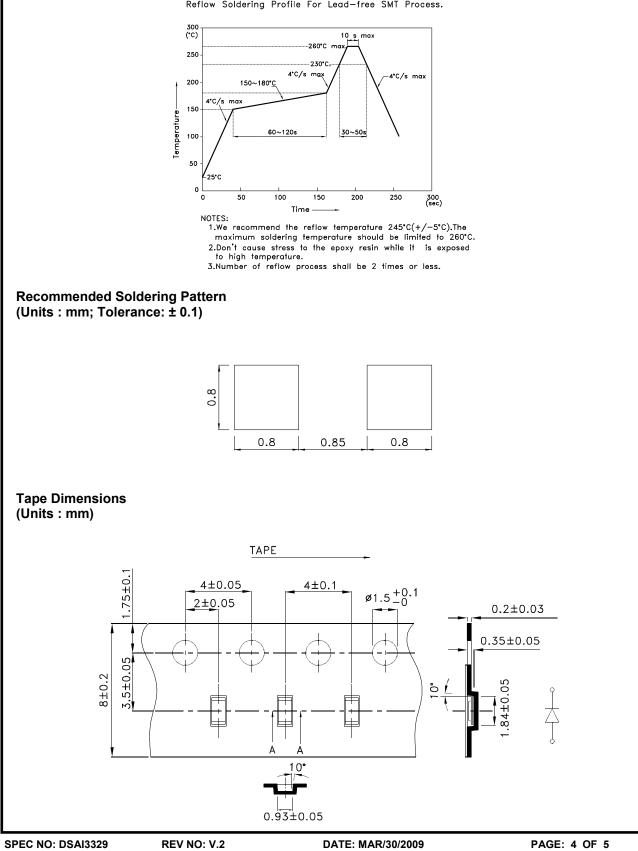
1. 1/10 Duty Cycle, 0.1ms Pulse Width.



APG1608SEKC/T

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



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